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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

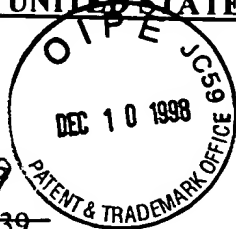
In re application of

Allen

Serial No.: 09/138,039

"SEGMENTED DIE FOR APPLYING  
HOT MELT ADHESIVES OR OTHER  
POLYMER MELTS (Case No. 35A)"

Commissioner of  
Patents and Trademarks  
Washington, D.C. 20231



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BEFORE THE EXAMINER

Group Unit:

Examiner:

Lubbock, Texas

December 5, 1998

**RECEIVED**

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3/13/99  
4/13/99

INVENTOR DISCLOSURE STATEMENT **GROUP 1700**

Sir:

Enclosed is Form 1449 "Inventor Disclosure Statement" and copies of documents cited therein. The documents are discussed below.

U.S. Patents 3,849,241; 4,073,850; 4,526,733 each disclose a meltblown die, but none are of segmented construction.

U.S. Patent 4,478,624 discloses a circular device and is not of segmented construction.

U.S. Patents 4,687,137 and 4,708,619 each disclose a monofilament dispenser, but neither is air assisted in dispensing the filaments—only beads are dispensed.

U.S. Patent 4,785,996 discloses a single unit spray gun.

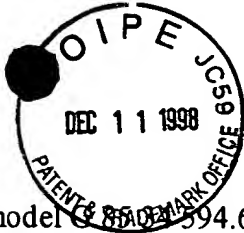
U.S. Patent 4,815,660 discloses a pair of side-by-side spray guns.

U.S. Patent 4,891,249 discloses a hot melt applicator comprising in at least one embodiment, two applications, but not of segmented construction.

U.S. Patent 4,983,109 discloses a spray head provided with a plurality of spiral nozzles. The spray head is not of segmented construction.

U.S. Patents 5,145,689; 5,236,641, and 5,382,312 each disclose a meltblowing die, but none of the dies disclosed comprise separable segmented modules.

U.S. Patent 5,679,379 discloses a modular die comprised of a stack-up of plates. There is no disclosure of a segmented manifold having a die module mounted on each manifold segment.



Germany utility model 85 024 594.6 discloses a spray head. There is no disclosure of a segmented structure comprising a segmented manifold and a die module mounted on each segment.

PCT US93/06434 discloses a slot die but does not disclose a segmented die.

The Trends article discloses a metering die but does not disclose the segmented manifold having a die module mounted on each segment.

The undersigned hereby certifies that this correspondence will be deposited on Dec 4, 1998 as first class mail with the United States Postal Service in an envelope addressed to the Commissioner of Patents and Trademarks, Washington, D.C. 20231.

12/4/98

Date of Signature

Respectfully submitted,

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